



PRODUCT SPECIFICATION

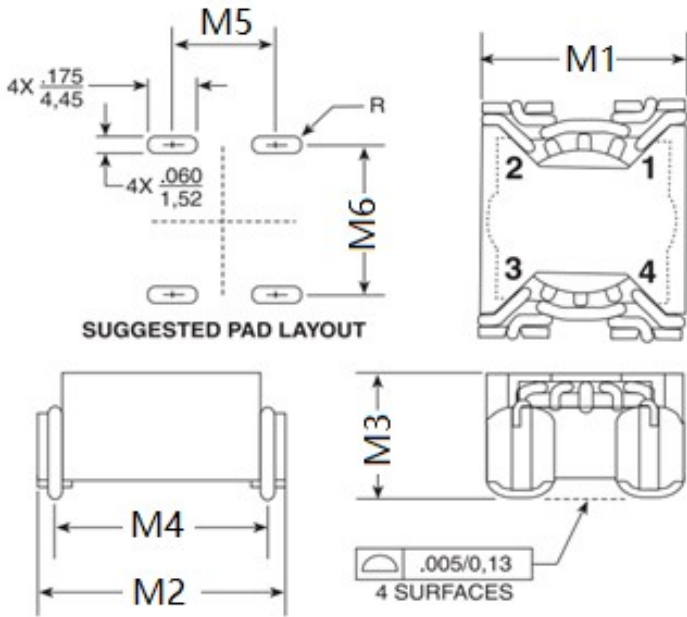
DOCUMENT NO.ENS000176160

DESCRIPTION	DRAWN BY	DESIGNED BY	CHECKED BY	APPROVED BY
OX1411SI-602IH	Zhuoling Tang	Tieqiao Gong	Tieqiao Gong	Dick Wang

ENGINEERING CHANGE NOTICE – RECORD

REVISION NO.	REVISION DESCRIPTION	AUTHOR	DATE	REMARK
P0		<i>Tieqiao Gong</i>	2023/1/31	

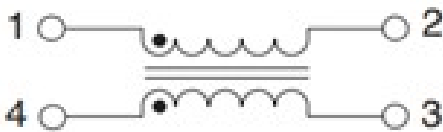
MECHANICAL DIMENSION



UNIT: mm

	DIM.	TOL.
M1	14.22	MAX.
M2	16.38	MAX.
M3	8.89	MAX.
M4	13.21	±0.5
M5	8.64	±0.5
M6	13.46	±0.5

SCHEMATIC DIAGRAM / CONSTRUCTION



ELECTRICAL SPECIFICATION

Inductance(1-2/4-3) (mH) MIN.	Test Frequency (KHz/V)	Rated Current (A) MAX.	Turn Ratio ±2%	DCR (mΩ) MAX.	HI-POT COIL-COIL 5mA/2s
6	10/0.1	1	1:1	450	500V AC

TEST INSTRUMENT: CH3302&CH16502BC&CH19053
 OPERATING TEMP RANGE:-40°C to +125°C
 STORAGE TEMP RANGE: -20°C to +85°C

WINDING DATA

WIRE: 0.25 ∅mm

TURNS: 36 Ts (REF.)

MATERIAL LIST

MATERIAL CATEGORY	MATERIAL TYPE	RATING	SUPPLIERS	SGS NO.	UL NO.
WIRE	SFBW-2@	155°C	JUNG SHING WIRE CO LTD. OR EQUIV.	KA/2020/20751A-02	E174837
CORE	PM10K	-	PING XIN CORES ELECTRONIC CO.,LTD. OR EQUIV.	A2200129680101001	-
	A10	-	ACME ELECTRONICS CORPORATION OR EQUIV.	CE/2020/90068A	-
SOLDER	Sn99.3%,Cu0.7%,熔 點 227°C,HF	-	DONGGUAN YONGAN TECHNOLOGY CO.,LTD OR EQUIV.	CANEC2004108907	-
BASE	KTSM1231-4	-	-	-	-
EPOXY	909AB		DONG GUAN HUA CHUANG ELECTRONIC MATERIAL FACTORY OR EQUIV.	A2200403250101009	-
VARNISH	AC-43	155°C	JOHN C DOLPH CO. OR EQUIV.	BOC7FCYR93102704	E317427

RELIABILITY PERFORMANCE

Reliability Experiment For Electrical

Test Item	Accept criteria	Test Condition	Standard Source
Humidity Test	1.Change from an initial value L:within±5% 2.no visible damage.	+40°C± 2°C, humidity of 90% ±5% (total 96 hours).	MIL-STD-202H Method 103 Test Condition B
High Temperature Test	1.Change from an initial value L:within±5% 2.no visible damage.	1.Temperature: +125°C±2°C. 2.Test time: 72±2hrs.	IEC 68-2 Test Condition B
Low Temperature Test	1.Change from an initial value L:within±5% 2.no visible damage.	1.Temperature: -25°C±2°C. 2.Test time: 72±2hrs.	IEC 68-2 Test Condition A
Thermal Shock	1.Change from an initial value L:within±5% 2.no visible damage.	+125°C±5°C (30 minutes) ~ -65±5°C (30 minutes), temperature switch time: 5 minutes (total 50 cycles).	Reference MIL-STD-202H Method 107 Test Condition B-2
Life Test	1.Change from an initial value L:within±5% 2.no visible damage.	+70°C±5°C (250Hours).	Reference MIL-STD-202H Method 108 Test Condition B

Reliability Experiment For Physical

Test Item	Accept criteria	Test Condition	Standard Source
Vibration Test	1.Change from an initial value L:within±5% 2.no visible damage.	10-55-10HZ, amplitude: 1.5mm, direction: X, Y, Z axes, each axis 2 hours (total 6 hours).	MIL-STD-202H Method 201
Solder Heat Resistance Test	1.no visible damage.	DIP: Soak in 260°C solder pot, stay 10Sec.	MIL-STD-202H Method 210 Test Condition D (DIP)
Solder Ability Test	1. Lead must have 95% above coverage.	Solder temp: 245±5°C, Immersion time: 5 second. Immersion rate: 25±6mm/sec.	J-STD-002D Test condition B1

REFLOW CHART

WAVE SOLDERING PROFILE

